OSRAM V105Q121A-850

Datasheet

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BIDOS® P2433 Q

V105Q121A-850

850 nm Multi-Mode VCSEL Power Array
Designed for Sensor Field of Interest : 60° x 45°

Applications

- Access Control & Security

Features

- Package: QFN Package
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- Very small SMT package
- VCSEL power array
- High optical power
- IR Laser with photodiode

Ordering Information

Type	Optical output power typ. P_{opt}	Ordering Code
V105Q121A-850	3 W	Q65113A5438

Depending on the mode of operation, these devices emit highly concentrated visible and non-visible light which can be hazardous to the human eye. Products which incorporate these devices must follow the safety precautions given in the “Notes” section.

Maximum Ratings

T_A = 25 °C

Parameter	Symbol		Values
Operating temperature (refers to T_A; T_A = 85°C with reduced efficiency)	T_{op}	min. max.	-20 °C 85 °C
Storage temperature	T_{stg}	min. max.	-40 °C 100 °C
Soldering temperature t_{max} = 10 s	T_S	max.	260 °C
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}	max.	2 kV
IR Laser			
Junction temperature	T_j	max.	125 °C
Forward current pulsed $t_p \leq 500$ µs; D = 0.01	$I_{F\ pulse}$	max.	6 A
Reverse voltage [5)]	V_R		Not designed for reverse operation
Photodiode			
Reverse voltage [5)]	V_R	max.	20 V
Breakdown voltage	V_{BR}	min.	50 V

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.

Characteristics

t_p = 300 µs; D = 0.05; T_A = 25 °C

Parameter	Symbol		Values
IR Laser			
Peak wavelength [6]	λ_{peak}	min.	840 nm
		typ.	850 nm
		max.	860 nm
Optical output power [7] I_F = 4 A	P_{opt}	min.	2.4 W
		typ.	3.00 W
Field of view (HFOV) Angle at Ee,50% level, normalized to the centroid	$\Theta_{\parallel}$	typ.	63 °
Field of view (VFOV) Angle at Ee,50% level, normalized to the centroid	$\Theta_{\perp}$	typ.	50 °
Dimensions of chip area	L x W	typ.	0.9 x 1.0 mm x mm
Slope efficiency I_F = 1 A … 2 A	η	typ.	0.95 W/ A
Power conversion efficiency I_F = 4 A	η_{tot}	typ.	38 %
Threshold current	I_{th}	typ.	0.9 A
Forward voltage [8] I_F = 4 A	V_F	min.	1.95 V
		typ.	2.10 V
		max.	2.45 V
Rise time 10% and 90% of $I_{e\,max}$	t_r	typ.	1 ns
Fall time 10% and 90% of $I_{e\,max}$	t_f	typ.	1 ns
Temperature coefficient of wavelength	TC_λ	typ.	0.06 nm/ K
Thermal resistance junction solder point real t_p = 0.01 s	$Rth_{JS\,real}$	max.	11 K/ W

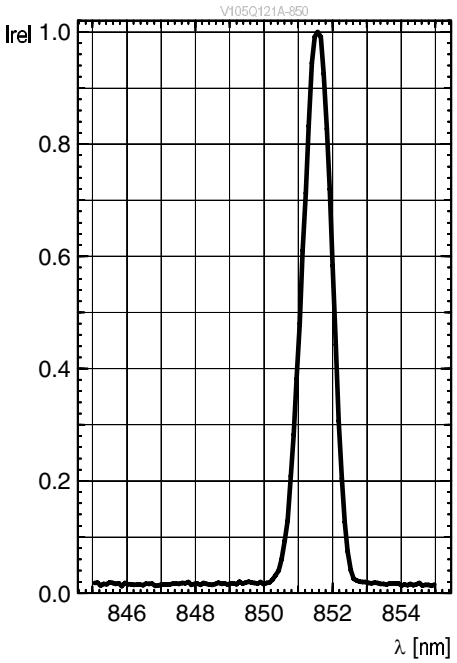
Characteristics

T_A = 25 °C

Parameter	Symbol		Values
Photodiode			
Wavelength of max sensitivity	$\lambda_{S\ max}$	typ.	800 nm
Spectral range of sensitivity	$\lambda_{10\%}$	typ.	450 … 1050 nm
Photocurrent λ = 850 nm, E_e = 0.5 mW/cm², V_R = 3.3 V	I_P	typ.	0.25 µA
Photocurrent [9] with VCSEL @ I_F = 4 A; λ = 850 nm; V_R = 3.3 V	I_P	typ.	0.50 mA
Dimensions of chip area	L x W	typ.	0.38 x 0.38 mm x mm
Dark current V_R = 3.3 V, E = 0	I_R	typ. max.	0.1 nA 30 nA
Open-circuit voltage λ = 850 nm, E_e = 0.5 mW/cm²	V_O	typ.	320 mV
Short-circuit current λ = 850 nm, E_e = 0.5 mW/cm², V_R = 0 V	I_{SC}	typ.	235 nA
Rise time 10 %/ 90%; λ = 850 nm	t_r	typ.	1 ns
Fall time 10 %/ 90%; λ = 850 nm	t_f	typ.	1 ns
Forward voltage I_F = 10 mA, E = 0	V_F	typ. max.	0.85 V 1.00 V
Capacitance E_e = 0 mW/cm², f = 1 MHz, V_R = 0 V	C_0	typ.	2 pF
Temperature coefficient of sensitivity λ = 940 nm, E_e = 0.5 mW/cm², V_R = 3.3 V	TC_I	typ.	0.23 %/ K

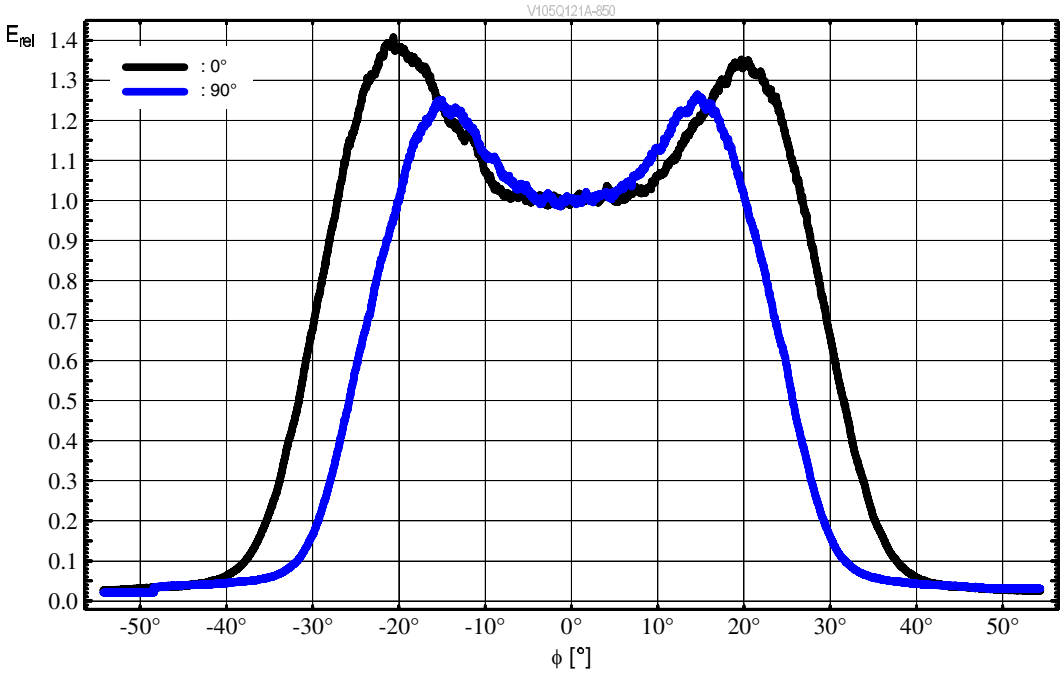
Relative Spectral Emission [1], [2]

- infrared (850 nm): $I_{e,rel} = f(\lambda)$; I_F = 4000 mA; t_p = 300 µs



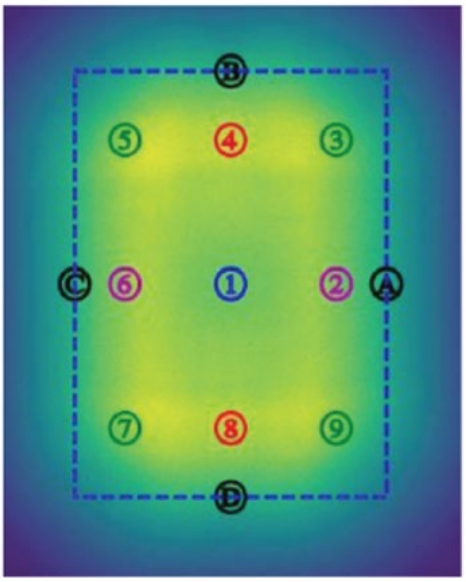
Radiation Characteristics [1], [2]

- infrared (850 nm): $E_{e,rel} = f(\varphi)$; I_F = 4000 mA; t_p = 300 µs; D = 0.05



Far-Field Illumination Pattern [2)]

- infrared (850 nm): $I_{e,rel} = f(\varphi)$; I_F = 4000 mA; t_p = 300 µs; D = 0.05

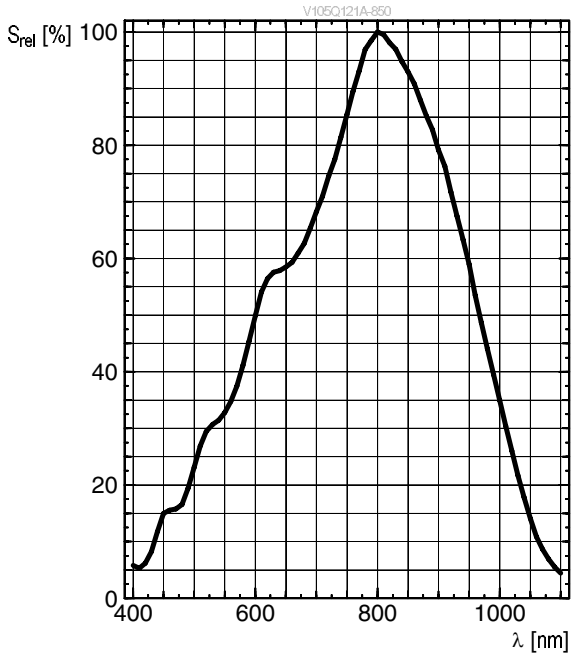


Sensor FOI 60°(H) x 45°(V) (dotted line)

	Min	Typ	Max
1	100%	100%	100%
2	100%	120%	140%
3	110%	135%	160%
4	110%	133%	155%
5	110%	135%	160%
6	100%	120%	140%
7	110%	135%	160%
8	110%	133%	155%
9	110%	135%	160%
A	65%	85%	105%
B	70%	90%	110%
C	65%	85%	105%
D	70%	90%	110%

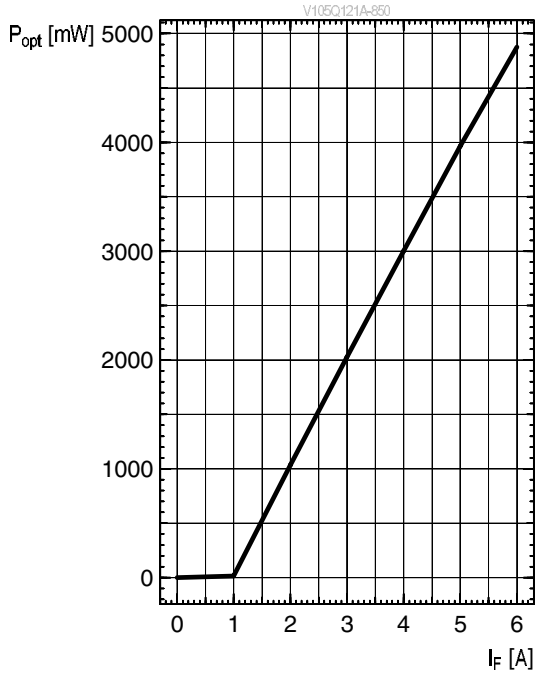
Relative Spectral Sensitivity [1], [2]

■ photodiode: $S_{rel} = f(\lambda)$



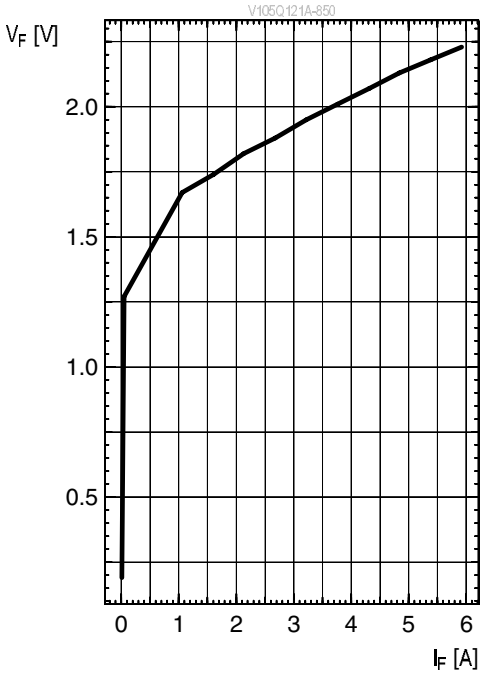
Optical Output Power [1], [2]

● infrared (850 nm): $P_{opt} = f(I_F)$; t_p = 300 µs; D = 0.05



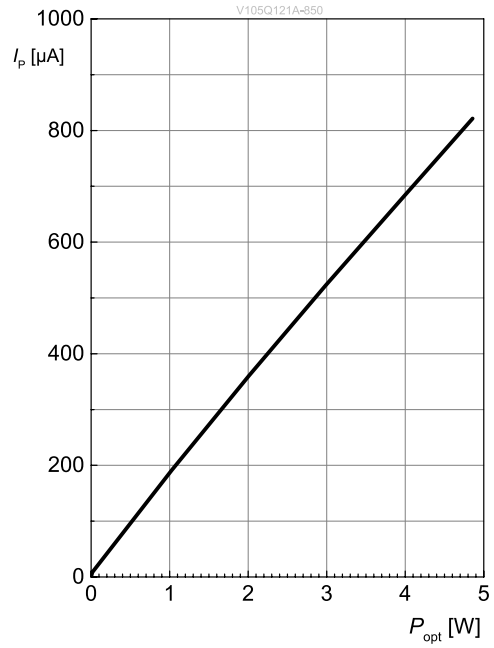
Forward Voltage [1], [2]

● infrared (850 nm): $V_F = f(I_F)$; t_p = 300 µs; D = 0.05



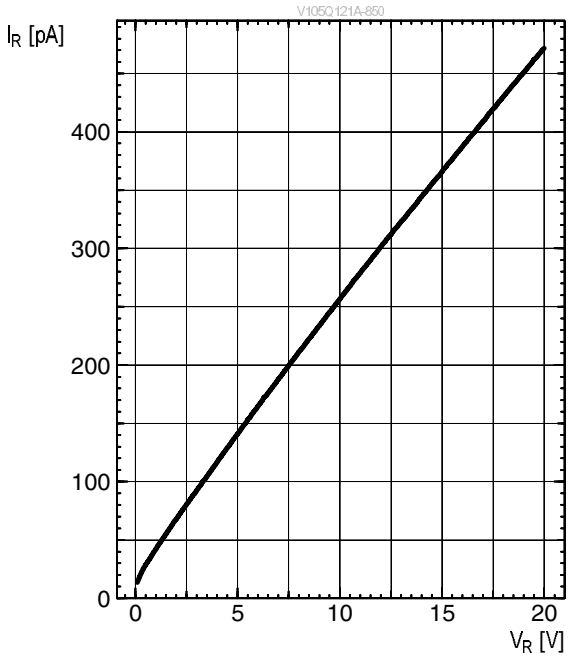
Photocurrent 1), 2)

- photodiode: $I_P = f(P_{opt})$; V_R = 3.3 V



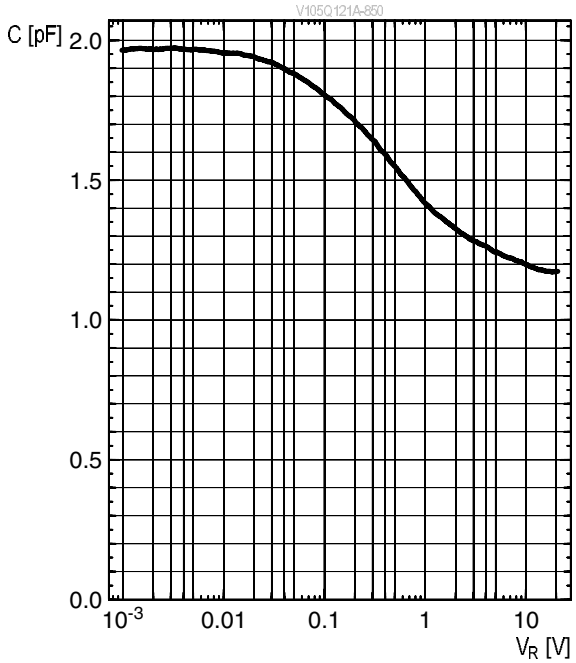
Dark Current 1), 2)

- photodiode: $I_R = f(V_R)$



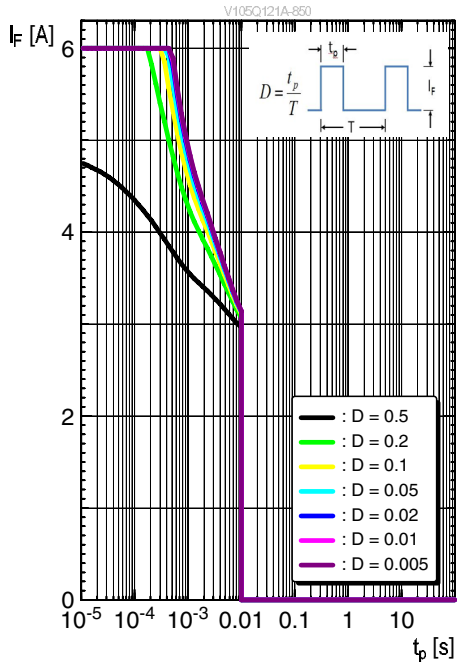
Capacitance 1), 2)

- photodiode: $C = f(V_R)$;



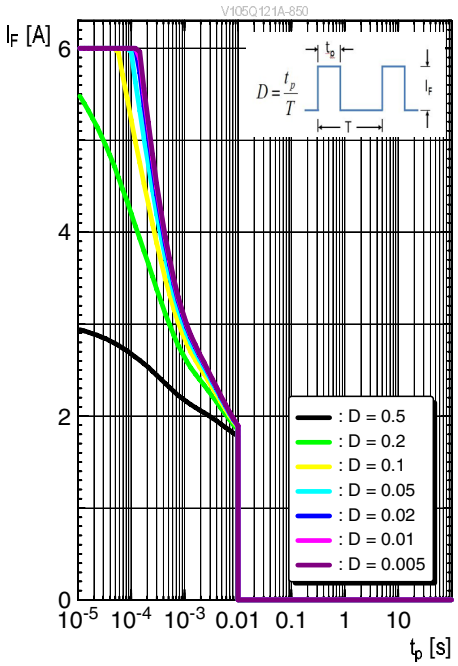
Permissible Pulse Handling Capability

- infrared (850 nm): $I_F = f(t_p)$; D = param.; T_A = 25 °C

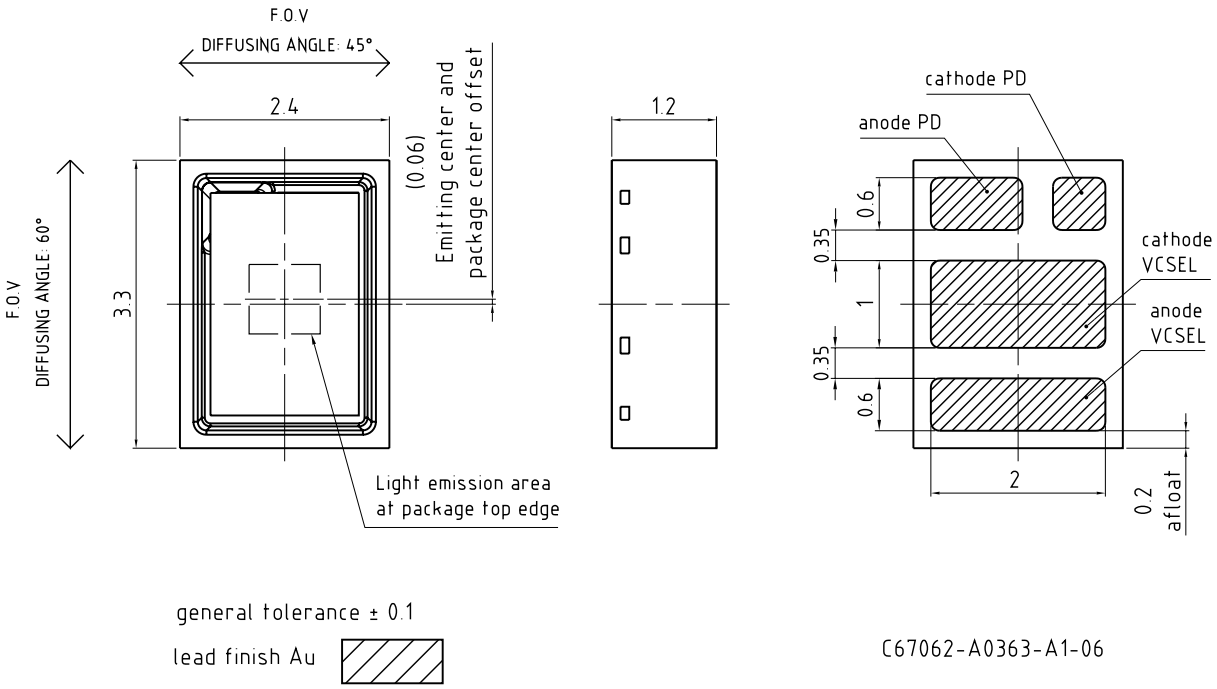


Permissible Pulse Handling Capability

- infrared (850 nm): $I_F = f(t_p)$; D = param.; T_A = 85 °C



Dimensional Drawing [3)]



general tolerance ± 0.1

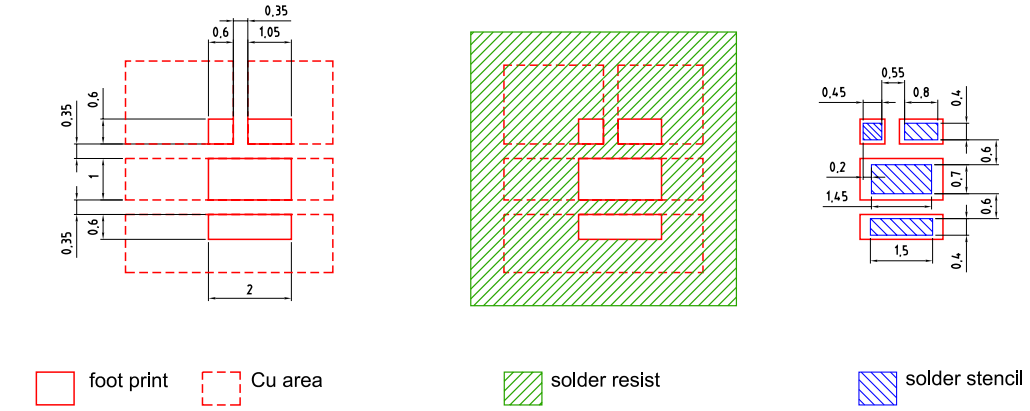
lead finish Au

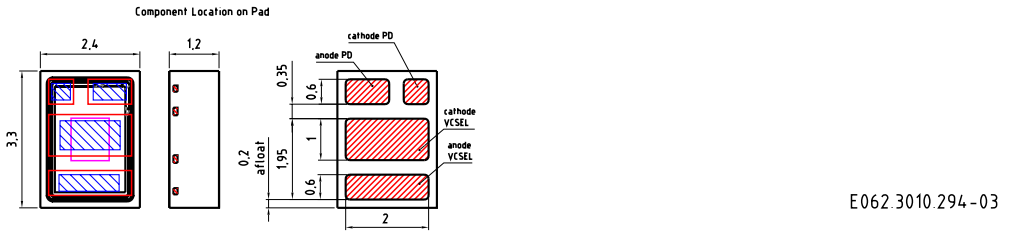
C67062-A0363-A1-06

Further Information:

Approximate Weight: 20.0 mg

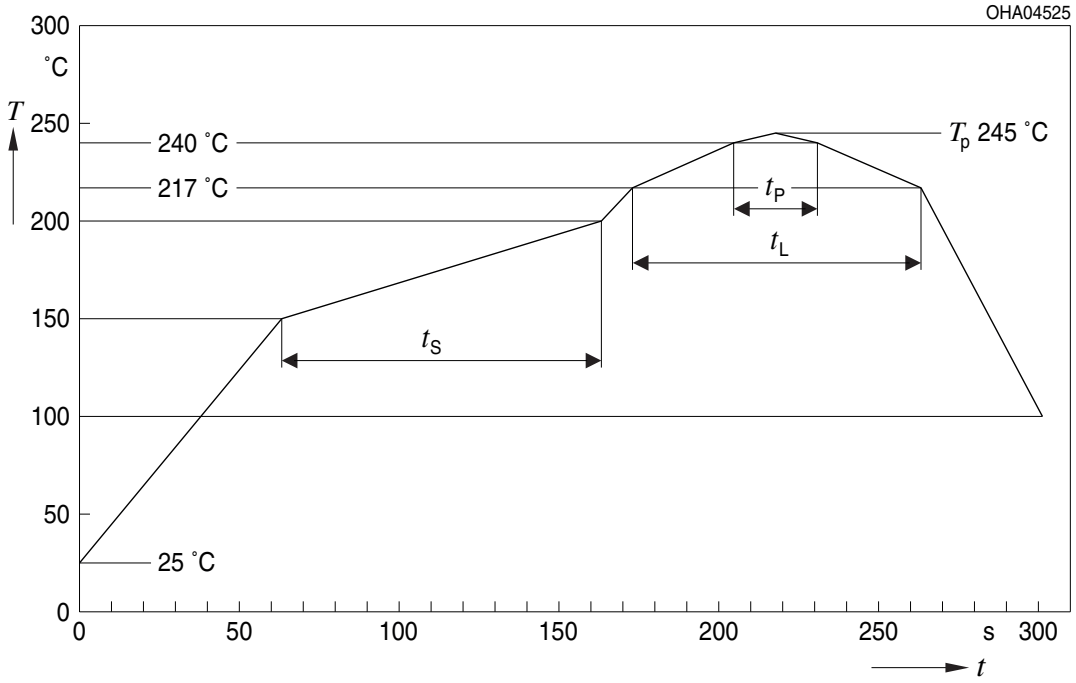
Recommended Solder Pad [3)]





Reflow Soldering Profile

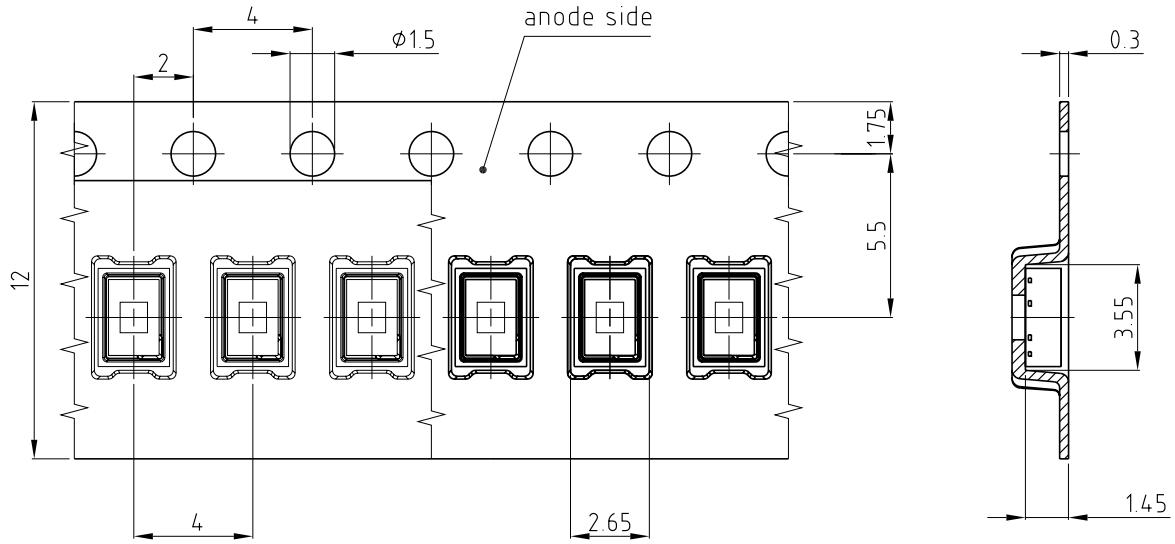
Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping [3)]



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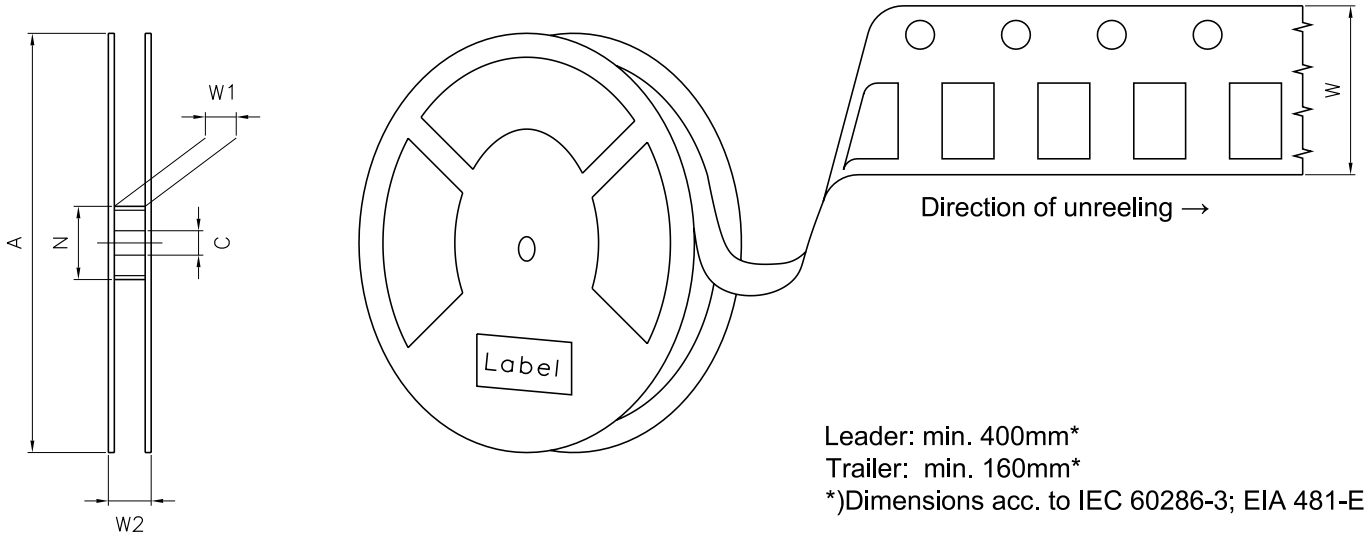
Tape and Reel [4)]

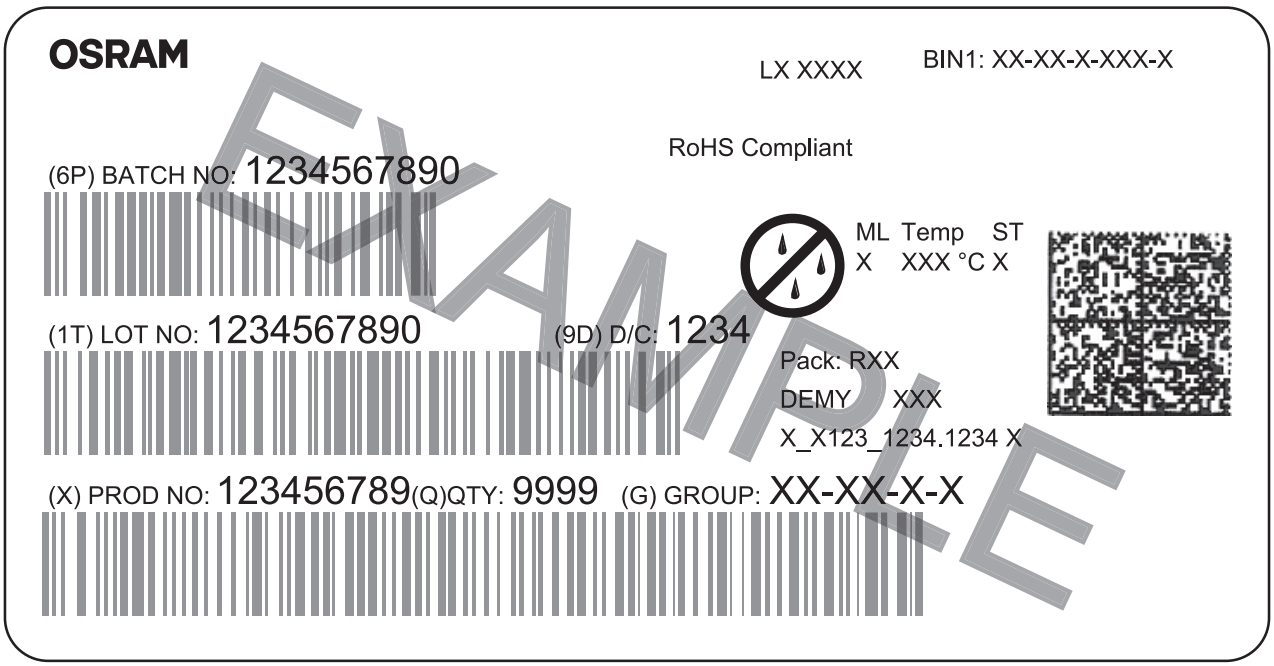


Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel Dimensions

A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	2000

Barcode-Product-Label (BPL)



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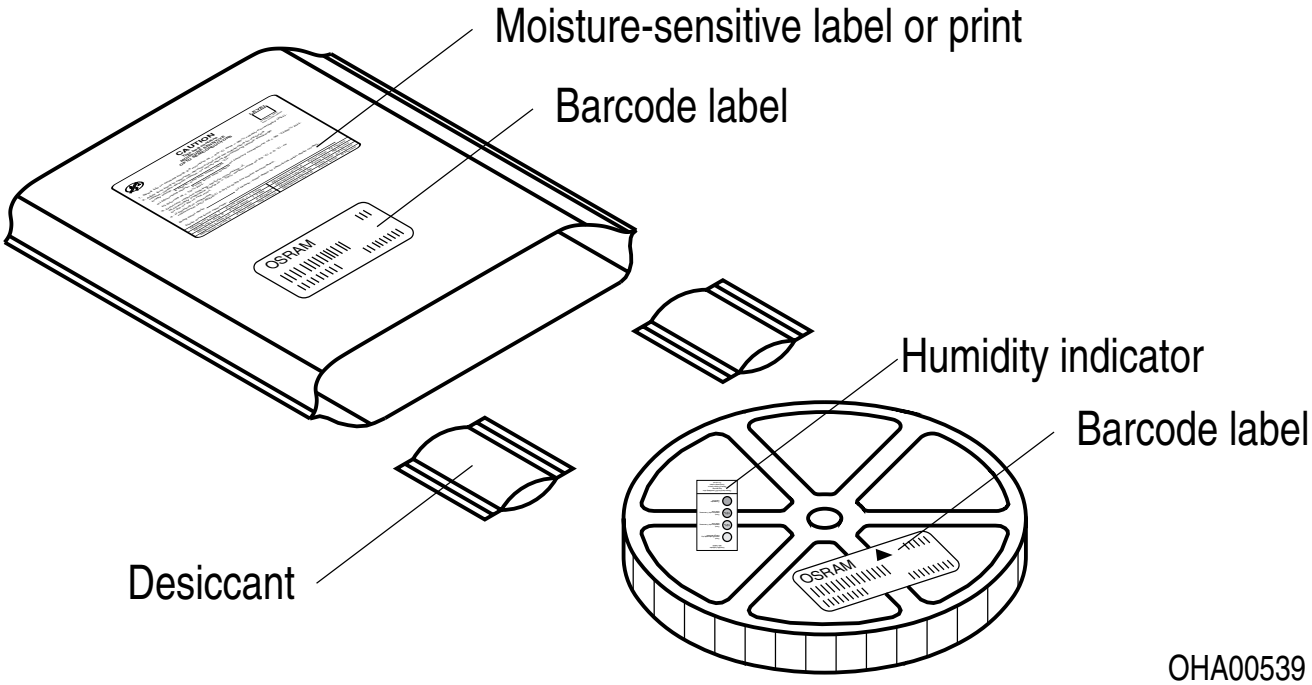
Dry Packing Process and Materials



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Notes

Depending on the mode of operation, these devices emit highly concentrated visible and non visible light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit https://ams-osram.com/support/application-notes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.
Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

1) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
2) **Testing temperature:** T_A = 25°C (unless otherwise specified)
3) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
4) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.
5) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
6) **Wavelength:** The wavelengths are measured with a tolerance of ±1 nm.
7) **Brightness:** The brightness values are measured with a tolerance of ±11%.
8) **Forward Voltage:** The forward voltages are measured with a tolerance of ±0.1 V.
9) **Photocurrent:** The photocurrent values are measured (by irradiating the devices with a homogenous light source and applying a voltage to the device) with a tolerance of ±11 %.

Revision History

Version	Date	Change
1.0	2023-11-23	Initial Version
1.1	2024-06-26	Recommended Solder Pad Taping
1.2	2025-02-04	Characteristics

EU RoHS and China RoHS compliant product
此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，
不含有毒有害物质或元素。

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